ABSTRACT

HEAT-TREATMENT FURNACE

The disclosed heat-treatment furnace, used in a semiconductor-substrate heat-treatment step, is characterized by the provision of a cylindrical core, both ends of which have openings sized so as to allow insertion and removal of semiconductor substrates. This reduces standby time between batches during consecutive semiconductor heat treatment, thereby improving productivity. Furthermore, the use of a simple cylindrical shape for the structure of the core reduces the frequency at which gas-introduction pipe sections fail, thereby decreasing the running cost of the heat-treatment process.